Features

- Fast Read Access Time 90 ns
- Low Power CMOS Operation
 - 100 μA Max Standby
 - 40 mA Max Active at 5 MHz
- JEDEC Standard Packages
 - 32-lead PLCC
 - 32-lead 600-mil PDIP
 - 32-lead TSOP
- 5V ±10% Supply
- High-Reliability CMOS Technology
 - 2,000V ESD Protection
 - 200 mA Latchup Immunity
- Rapid[™] Programming Algorithm 50 µs/Byte (Typical)
- CMOS and TTL Compatible Inputs and Outputs
- Integrated Product Identification Code
- Industrial and Commercial Temperature Ranges

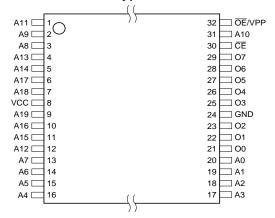
Description

The AT27C080 chip is a low-power, high-performance 8,388,608-bit one-time programmable read only memory (OTP EPROM) organized as 1M by 8 bits. The AT27C080 requires only one 5V power supply in normal read mode operation. Any byte can be accessed in less than 90 ns, eliminating the need for speed reducing WAIT states on high-performance microprocessor systems.

Pin Configurations

Pin Name	Function
A0 - A19	Addresses
O0 - O7	Outputs
CE	Chip Enable
OE/VPP	Output Enable/ Program Supply

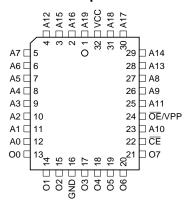
TSOP Top View Type 1



PDIP Top View

-			
		$\overline{\bigcirc}$	1
A19 □	1	32	⊐ vcc
A16 □	2	31	□ A18
A15 🗆	3	30	□ A17
A12 🗆	4	29	□ A14
A7 □	5	28	□ A13
A6 □	6	27	□ A8
A5 □	7	26	□ A9
A4 □	8	25	□ A11
А3 □	9	24	□ OE /VPP
A2 🗆	10	23	□ A10
A1 🗆	11	22	□ CE
A0 🗆	12	21	□ 07
O0 □	13	20	□ O6
01 □	14	19	□ O5
O2 🗆	15	18	□ O4
GND □	16	17	□ O3

PLCC Top View





8-Megabit (1M x 8) OTP EPROM

AT27C080







Atmel's scaled CMOS technology provides low active power consumption and fast programming. Power consumption is typically 10 mA in active mode and less than 10 μ A in standby mode.

The AT27C080 is available in a choice of packages, including; one-time programmable (OTP) plastic PLCC, PDIP and TSOP. All devices feature two-line control (\overline{CE} , \overline{OE}) to give designers the flexibility to prevent bus contention.

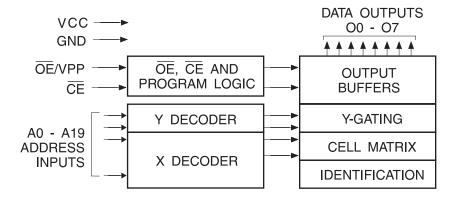
With high density 1M byte storage capability, the AT27C080 allows firmware to be stored reliably and to be accessed by the system without the delays of mass storage media.

Atmel's AT27C080 has additional features to ensure high quality and efficient production use. The Rapid Programming Algorithm reduces the time required to program the part and guarantees reliable programming. Programming time is typically only 50 μ s/byte. The Integrated Product Identification Code electronically identifies the device and manufacturer. This feature is used by industry standard programming equipment to select the proper programming algorithms and voltages.

System Considerations

Switching between active and standby conditions via the Chip Enable pin may produce transient voltage excursions. Unless accommodated by the system design, these transients may exceed datasheet limits, resulting in device non-conformance. At a minimum, a 0.1 μF high frequency, low inherent inductance, ceramic capacitor should be utilized for each device. This capacitor should be connected between the V_{CC} and Ground terminals of the device, as close to the device as possible. Additionally, to stabilize the supply voltage level on printed circuit boards with large EPROM arrays, a 4.7 μF bulk electrolytic capacitor should be utilized, again connected between the V_{CC} and Ground terminals. This capacitor should be positioned as close as possible to the point where the power supply is connected to the array.

Block Diagram



Absolute Maximum Ratings*

Temperature Under Bias55°C to +125°C
Storage Temperature65°C to +150°C
Voltage on Any Pin with Respect to Ground2.0V to +7.0V ⁽¹⁾
Voltage on A9 with Respect to Ground2.0V to +14.0V ⁽¹⁾
V _{PP} Supply Voltage with Respect to Ground2.0V to +14.0V ⁽¹⁾
Integrated UV Erase Dose7258 W•sec/cm²

*NOTICE: Stresses beyond those listed under "Absolute

Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended

periods may affect device reliability.

Note: 1. Minimum voltage is -0.6V DC which may undershoot to -2.0V for pulses of less than 20 ns. Maximum output pin voltage is V_{CC} + 0.75V DC which may overshoot to +7.0V for pulses of less than 20 ns.

Operating Modes

Mode/Pin	CE	OE/V _{PP}	Ai	Outputs
Read	V _{IL}	V _{IL}	Ai	D _{OUT}
Output Disable	X	V _{IH}	X ⁽¹⁾	High Z
Standby	V _{IH}	Х	Х	High Z
Rapid Program ⁽²⁾	V _{IL}	V _{PP}	Ai	D _{IN}
PGM Verify	V _{IL}	V _{IL}	Ai	D _{OUT}
PGM Inhibit	V _{IH}	V _{PP}	Х	High Z
Product Identification ⁽⁴⁾	V _{IL}	V _{IL}	$A9 = V_H^{(3)}$ $A0 = V_{IH} \text{ or } V_{IL}$ $A1 - A19 = V_{IL}$	Identification Code

Notes: 1. X can be V_{IL} or V_{IH.}

- 2. Refer to Programming Characteristics.
- 3. $V_H = 12.0 \pm 0.5 V$.
- 4. Two identifier bytes may be selected. All Ai inputs are held low (V_{IL}), except A9 which is set to V_H and A0 which is toggled low (V_{IL}) to select the Manufacturer's Identification byte and high (V_{IH}) to select the Device Code byte.





DC and AC Operating Conditions for Read Operation

_		AT27C080-90	AT27C080-10	AT27C080-12	AT27C080-15
Operating Temperature (Case)	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C
	Ind.	-40° C - 85° C			
V _{CC} Power Supply		5V ± 10%	5V ± 10%	5V ± 10%	5V ± 10%

DC and Operating Characteristics for Read Operation

Symbol	Parameter	Condition	Min	Max	Units
ILI	Input Load Current	$V_{IN} = 0V$ to V_{CC} (Com., Ind.)		±1.0	μΑ
I _{LO}	Output Leakage Current	$V_{OUT} = 0V$ to V_{CC} (Com., Ind.)		±5.0	μΑ
I _{SB}	V _{CC} ⁽¹⁾ Standby Current	I_{SB1} (CMOS), $\overline{CE} = V_{CC} \pm 0.3V$		100	μΑ
		I_{SB2} (TTL), \overline{CE} = 2.0 to V_{CC} + 0.5V		1.0	mA
I _{CC}	V _{CC} Active Current	$f = 5 \text{ MHz}, I_{OUT} = 0 \text{ mA}, \overline{CE} = V_{IL}$		40	mA
V _{IL}	Input Low Voltage		-0.6	0.8	٧
V _{IH}	Input High Voltage		2.0	V _{CC} + 0.5	V
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		0.4	V
V _{OH}	Output High Voltage	I _{OH} = -400 μA	2.4		V

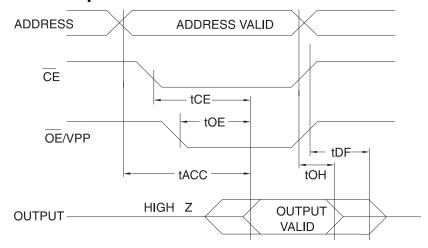
Notes: 1. V_{CC} must be applied simultaneously or before \overline{OE}/V_{PP} , and removed simultaneously or after \overline{OE}/V_{PP} .

AC Characteristics for Read Operation

			AT27C080								
			-9	90		10		12		15	
Symbol	Parameter	Condition	Min	Max	Min	Max	Min	Max	Min	Max	Units
t _{ACC} ⁽⁴⁾	Address to Output Delay	$\overline{CE} = \overline{OE}/V_{PP}$ = V_{IL}		90		100		120		150	ns
t _{CE} ⁽³⁾	CE to Output Delay	OE = V _{IL}		90		100		120		150	ns
t _{OE} (3)(4)	OE to Output Delay	CE = V _{IL}		20		20		30		35	ns
t _{DF} ⁽²⁾⁽⁵⁾	OE or CE High to Output Float occurred first		30		30		35		40	ns	
t _{OH}	Output Hold from Address, CE or OE/V _{PP} whichever occurred	0		0		0		0		ns	

Notes: 1. 2, 3, 4, 5. See AC Waveforms for Read Operation.

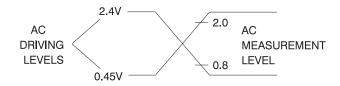
AC Waveforms for Read Operation(1)



Notes: 1. Timing measurement references are 0.8V and 2.0V. Input AC drive levels are 0.45V and 2.4V, unless otherwise specified.

- 2. t_{DF} is specified form OE/VPP or CE, whichever occurs first. Output float is defined as the point when data is no longer driven.
- 3. \overline{OE}/V_{PP} may be delayed up to t_{CE} t_{OE} after the falling edge of \overline{CE} without impact on t_{CE} .
- 4. \overline{OE}/V_{PP} may be delayed up to t_{ACC} t_{OE} after the address is valid without impact on t_{ACC} .
- 5. This parameter is only sampled and is not 100% tested.

Input Test Waveform and Measurement Levels



 t_R , t_F < 20 ns (10% to 90%)

Output Test Load

Note: 1. CL = 100 pF including jig capacitance.

Pin Capacitance

 $f = 1 \text{ MHz}, T = 25^{\circ} C^{(1)}$

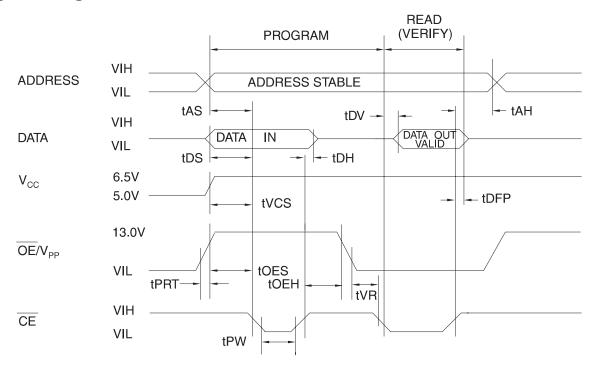
Symbol	Тур	Max	Units	Conditions	
C _{IN}	4	8	pF	$V_{IN} = 0V$	
C _{OUT}	8	12	pF	V _{OUT} = 0V	

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.





Programming Waveforms



1. The Input Timing reference is 0.8V for V_{IL} and 2.0V for V_{IH} .

2. t_{OE} and t_{DFP} are characteristics of the device but must be accommodated by the programmer.

DC Programming Characteristics

 $T_A = 25 \pm 5^{\circ}C$, $V_{CC} = 6.5 \pm 0.25V$, $\overline{OE}/V_{PP} = 13.0 \pm 0.25V$

			Lin	Limits	
Symbol	Parameter	Test Conditions	Min	Max	Units
ILI	Input Load Current	$V_{IN} = V_{IL}, V_{IH}$		±10	μА
V _{IL}	Input Low Level		-0.6	0.8	V
V _{IH}	Input High Level		2.0	V _{CC} + 1.0	V
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		0.4	V
V _{OH}	Output High Voltage	I _{OH} = -400 μA	2.4		V
I _{CC2}	V _{CC} Supply Current (Program and Verify)			40	mA
I _{PP2}	OE/V _{PP} Supply Current	CE = V _{IL}		25	mA
V _{ID}	A9 Product Identification Voltage		11.5	12.5	V

AC Programming Characteristics

 $T_A = 25 \pm 5$ °C, $V_{CC} = 6.5 \pm 0.25$ V, $\overline{OE}/V_{PP} = 13.0 \pm 0.25$ V

			Lir	nits	
Symbol	Parameter	Test Conditions ⁽¹⁾	Min	Min Max	
t _{AS}	Address Setup Time	Input Rise and Fall Times:	2.0		μs
t _{OES}	OE/V _{PP} Setup Time	(10% to 90%) 20 ns	2.0		μs
t _{OEH}	ŌE/V _{PP} Hold Time	Input Pulse Levels:	2.0		μs
t _{DS}	Data SetupTime	0.45V to 2.4V	2.0		μs
t _{AH}	Address Hold Time		0.0		μs
t _{DH}	Data Hold Time	Input Timing Reference Level: 0.8V to 2.0V	2.0		μs
t _{DFP}	CE High to Output Float Delay ⁽²⁾	0.07 to 2.07	0.0	130	ns
t _{VCS}	V _{CC} Setup Time	Output Timing Reference Level:	2.0		μs
t _{PW}	CE Program Pulse Width ⁽³⁾	0.8V to 2.0V	47.5	52.5	μs
t _{DV}	Data Valid from CE			1.0	μs
t _{VR}	OE/V _{PP} Recovery Time		2.0		ns
t _{PRT}	OE/V _{PP} Pulse Rise Time During Programming		50		ns

Atmel's AT27C080 Integrated Product Identification Code

		Pins								
Codes	Α0	07	06	O5	04	О3	O2	01	00	Hex Data
Manufacturer	0	0	0	0	1	1	1	1	0	1E
Device Type	1	1	0	0	0	1	0	1	0	8A

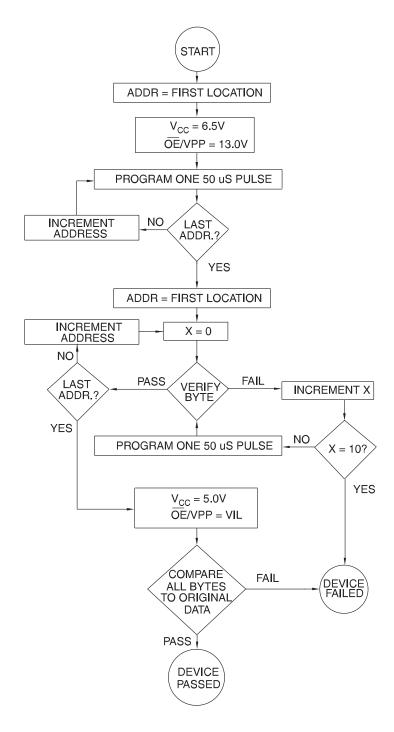
Notes: 1. V_{CC} must be applied simultaneously or before $\overline{\text{OE}/\text{V}_{PP}}$ and removed simultaneously or after $\overline{\text{OE}/\text{V}_{PP}}$ 2. This parameter is only sampled and is not 100% tested. Output Float is defined as the point where data is no longer driven – see timing diagram.

^{3.} Program Pulse width tolerance is 50 μ s \pm 5%.



Rapid Programming Algorithm

A 50 μs \overline{CE} pulse width is used to program. The address is set to the first location. V_{CC} is raised to 6.5V and \overline{OE}/V_{PP} is raised to 13.0V. Each address is first programmed with one 50 μs \overline{CE} pulse without verification. Then a verification reprogramming loop is executed for each address. In the event a byte fails to pass verification, up to 10 successive 50 μs pulses are applied with a verification after each pulse. If the byte fails to verify after 10 pulses have been applied, the part is considered failed. After the byte verifies properly, the next address is selected until all have been checked. \overline{OE}/V_{PP} is then lowered to V_{IL} and V_{CC} to 5.0V. All bytes are read again and compared with the original data to determine if the device passes or fails.



Ordering Information

t _{ACC}	I _{cc}	(mA)			
(ns)	(ns) Active Standby		Ordering Code	Package	Operation Range
90	40	0.1	AT27C080-90JC	32J	Commercial
			AT27C080-90PC	32P6	(0°C to 70°C)
			AT27C080-90TC	32T	
	40	0.1	AT27C080-90JI	32J	Industrial
			AT27C080-90PI	32P6	(-40° C to 85° C)
			AT27C080-90TI	32T	
100	40	0.1	AT27C080-10JC	32J	Commercial
			AT27C080-10PC	32P6	(0°C to 70°C)
			AT27C080-10TC	32T	
	40	0.1	AT27C080-10JI	32J	Industrial
			AT27C080-10PI	32P6	(-40° C to 85° C)
			AT27C080-10TI	32T	
120	40	0.1	AT27C080-12JC	32J	Commercial
			AT27C080-12PC	32P6	(0°C to 70°C)
			AT27C080-12TC	32T	
	40	0.1	AT27C080-12JI	32J	Industrial
			AT27C080-12PI	32P6	(-40° C to 85° C)
			AT27C080-12TI	32T	
150	40	0.1	AT27C080-15JC	32J	Commercial
			AT27C080-15PC	32P6	(0°C to 70°C)
			AT27C080-15TC	32T	
	40	0.1	AT27C080-15JI	32J	Industrial
			AT27C080-15PI	32P6	(-40° C to 85° C)
			AT27C080-15TI	32T	

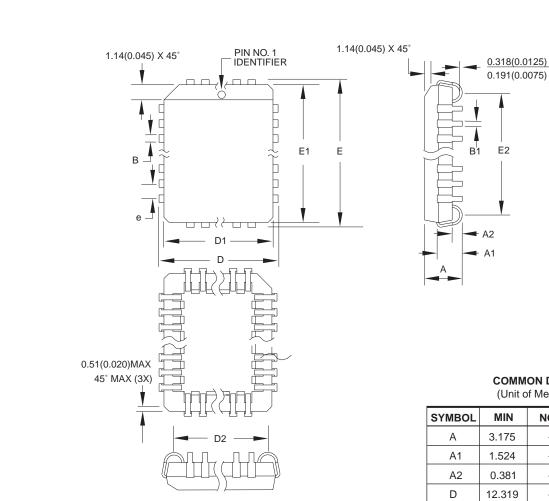
Package Type		
32J	32-lead, Plastic J-leaded Chip Carrier (PLCC)	
32P6	32-lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)	
32T	32-lead, Plastic Thin Small Outline Package (TSOP)	





Package Information

32J - PLCC



Notes:

- 1. This package conforms to JEDEC reference MS-016, Variation AE.
- Dimensions D1 and E1 do not include mold protrusion.
 Allowable protrusion is .010"(0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
- 3. Lead coplanarity is 0.004" (0.102 mm) maximum.

COMMON DIMENSIONS

(Unit of Measure = mm)

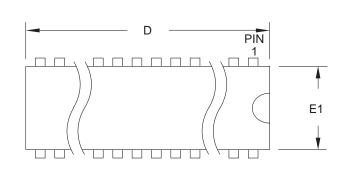
SYMBOL	MIN	NOM	MAX	NOTE
А	3.175	_	3.556	
A1	1.524	_	2.413	
A2	0.381	_	_	
D	12.319	_	12.573	
D1	11.354	_	11.506	Note 2
D2	9.906	_	10.922	
Е	14.859	-	15.113	
E1	13.894	_	14.046	Note 2
E2	12.471	_	13.487	
В	0.660	_	0.813	
B1	0.330	_	0.533	
е		1.270 TYP	•	

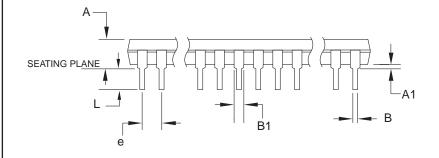
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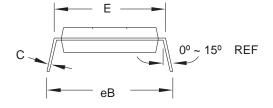
TITLE		
32J , 3	2-lead, Plastic J-leaded Chip Carrier (P	LCC)

DRAWING NO.	REV.
32J	В

32P6 - PDIP







Note: 1. Dimensions D and E1 do not include mold Flash or Protrusion.

Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
А	_	_	4.826	
A1	0.381	_	_	
D	41.783	_	42.291	Note 1
Е	15.240	_	15.875	
E1	13.462	_	13.970	Note 1
В	0.356	_	0.559	
B1	1.041	_	1.651	
L	3.048	_	3.556	
С	0.203	_	0.381	
eB	15.494	_	17.526	
е	2.540 TYP			

09/28/01



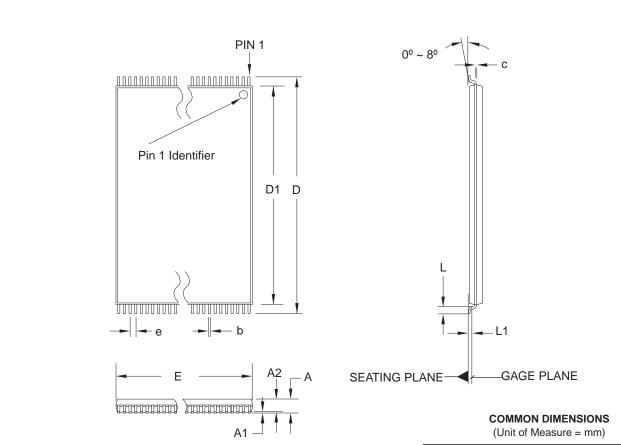
TITLE
32P6, 32-lead (0.600"/15.24 mm Wide) Plastic Dual Inline Package (PDIP)

DRAWING NO. REV. 32P6 B





32T - TSOP



Notes:

- 1. This package conforms to JEDEC reference MO-142, Variation BD.
- 2. Dimensions D1 and E do not include mold protrusion. Allowable protrusion on E is 0.15 mm per side and on D1 is 0.25 mm per side.
- 3. Lead coplanarity is 0.10 mm maximum.

SYMBOL	MIN	NOM	MAX	NOTE
А	_	_	1.20	
A1	0.05	_	0.15	
A2	0.95	1.00	1.05	
D	19.80	20.00	20.20	
D1	18.30	18.40	18.50	Note 2
Е	7.90	8.00	8.10	Note 2
L	0.50	0.60	0.70	
L1	0.25 BASIC			
b	0.17	0.22	0.27	
С	0.10	_	0.21	
е	0.50 BASIC			

10/18/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Pa San Jose, CA 9	7 I 321 32-lead (8 x 20 mm Package) Plastic Thin Small Outline	32T	В



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